

10.27.06

11-03-2006



103331585

1. Name of conveying parties:

- (1) **Wen-Hung HU**
 (2) **Ying-Tung WANG**
 (3) **Shih-Ping Hsu**
 (4) **Chao-Wen SHIH**

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No.

ss of receiving parties:

Name: **PHOENIX PRECISION TECHNOLOGY CORPORATION**Street Address: No. 6, Li-Hsin Road
Science-Based Industrial Park

City: Hsin-chu, TAIWAN R.O.C.

Additional name(s) and address(es) attached? ☐ Yes ☒ No.112955 U.S. PTO
11/588913

102706

10/31/2006 55111111 00000042 11388913
05 FC:8021

Assignment

40.00 DP

Execution dates: (1) **August 22, 2006**

- (2)
(3)
(4)

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is **August 22, 2006**

A. Patent Application No.(s)

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No5. Name and address of party to whom
correspondence concerning document should
be mailed:Name: **Sawyer Law Group LLP**
Address: **P.O. Box 51418**
Palo Alto, CA 943036. Total number of applications and patents involved: **One**7. Total fee (37 CFR 3.41)..... **\$ 40.00**☒ Enclosed☐ Authorized to be charged to deposit account

8. Deposit account number:

(Attach duplicate copy of this page if paying by deposit account)

9. Statement and signature.

*To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.***Joseph A. Sawyer, Jr.**

Name of Person Signing

Signature

10/22/06

Date

Total number of pages including cover sheet, attachments, and documents: (2)

ASSIGNMENT OF U.S. PATENT APPLICATION

In consideration of the sum of One Dollar in hand paid, and other good and valuable consideration, the receipt of which is hereby acknowledged, the undersigned

Inventor(s) (1) Wen-Hung HU (2) Ying-Tung WANG
 Full Name(s) (3) Shih-Ping HSU (4) Chao-Wen SHIH

Hereby sell, assign and transfer to

Assignee PHOENIX PRECISION TECHNOLOGY CORPORATION
 Name and Address No. 6, Li-Hsin Road, Science-Based Industrial Park,
Hsin-chu, Taiwan (R.O.C.)

(hereinafter called the Assignee) the entire right, title, and interest in and to any and all improvements which are disclosed in the Application for United States Letters Patent entitled

Title of Invention: CONDUCTIVE STRUCTURES FOR ELECTRICALLY CONDUCTIVE PADS
OF CIRCUIT BOARD AND FABRICATION METHOD THEREOF

Which application was

Complete either a) executed by the undersigned on _____
 b) filed on the _____
 Serial No. _____

Including any and all United States Letters Patents which may be granted therefore and any and all extensions, divisions, reissues, substitutes, renewals or continuations thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property.

It is hereby authorized and requested that the Commissioner of Patents issue any and all of said Letters Patent, when granted, to said assignee.

Further, it is agreed that, when requested, without charge to but at the expense of said Assignee, the undersigned will execute all divisional, continuing, substitute, renewal, and reissue patent applications; execute all rightful other papers; and generally do everything possible which said Assignee shall consider desirable for aiding in securing and maintaining proper patent protection.

Date _____ Signed at Taiwan (R.O.C.)
 On AUGUST 22, 2006

Inventor(s)	<u>Wen Hung Hu.</u>	<u>Wen-Hung HU</u>
Full Signature(s)	<u>ying tung wang</u>	<u>Ying-Tung WANG</u>
	<u>Shih-Ping HSU</u>	<u>Shih-Ping HSU</u>
	<u>Chao Wen Shih</u>	<u>Chao-Wen SHIH</u>